L Number	Hits	Search Text	DB	Time stamp
1	9	4778326.pn. 5590787.pn. 4990051.pn. 4850780.pn.	USPAT;	2004/08/05 09:01
		4915565.pn. 4759675.pn. 4285433.pn. 4607744.pn.	US-PGPUB	
		6202292.pn.		
2	5202	438/108.ccls. 438/113.ccls. 438/114.ccls. 438/459.ccls.	USPAT;	2004/08/05 09:03
		438/461.ccls. 438/464.ccls. 438/465.ccls. 438/977.ccls.	US-PGPUB	
		29/740.ccls. 29/743.ccls. 156/584.ccls.	_	
3	39	(438/108.ccls. 438/113.ccls. 438/114.ccls. 438/459.ccls.	USPAT;	2004/08/05 09:36
		438/461.ccls. 438/464.ccls. 438/465.ccls. 438/977.ccls.	US-PGPUB	
		29/740.ccls. 29/743.ccls. 156/584.ccls.) and (dbg (dic\$6		
_		near2 grind\$6))		2224422427 22 22
4	166	(dbg (dic\$6 near2 grind\$6))	EPO; JPO;	2004/08/05 09:06
			DERWENT;	
_	20	//	IBM_TDB	2004/00/05 42:02
6	28	((wafer dic\$6 protective) adj tape) same (release adj tape)	USPAT;	2004/08/05 13:03
_	_	((US-PGPUB	2004/00/05 00:20
7	3	((wafer dic\$6 protective) adj tape) and (release adj tape)	EPO; JPO;	2004/08/05 09:29
			DERWENT;	
	2	in 2002200072 # did	IBM_TDB	2004/09/05 00:20
8	2	jp-2003209073-\$.did.	EPO; JPO; DERWENT;	2004/08/05 09:30
			IBM TDB	
9	39	(438/108.ccls. 438/113.ccls. 438/114.ccls. 438/459.ccls.	USPAT;	2004/08/05 09:36
9	39	438/461.ccls. 438/464.ccls. 438/465.ccls. 438/977.ccls.	US-PGPUB	2004/00/03 09.30
		29/740.ccls. 29/743.ccls. 156/584.ccls.) and (dbg (dic\$6	05 (010)	
		near2 grind\$6))		
10	5	6297131.URPN.	USPAT	2004/08/05 11:30
11	2	("5960260" "6048749").PN.	USPAT	2004/08/05 11:41
5	108	((dbg (dic\$6 near2 grind\$6))) and (semiconductor wafer	EPO; JPO;	2004/08/05 12:04
5	100	package chip ic integrated die dice silicon tape)	DERWENT;	200 1, 00, 00 2210 1
		package ample integrated are also smooth cape,	IBM_TDB	
12	220	(438/108.ccls. 438/113.ccls. 438/114.ccls. 438/459.ccls.	USPAT;	2004/08/05 14:22
		438/461.ccls. 438/464.ccls. 438/465.ccls. 438/977.ccls.	US-PGPUB	, ,
		29/740.ccls. 29/743.ccls. 156/584.ccls.) and ((wafer dic\$6		
		protect\$6 releas\$6) adj tape)		
13	120	((438/108.ccls. 438/113.ccls. 438/114.ccls. 438/459.ccls.	USPAT;	2004/08/05 14:23
		438/461.ccls. 438/464.ccls. 438/465.ccls. 438/977.ccls.	US-PGPUB	
		29/740.ccls. 29/743.ccls. 156/584.ccls.) and ((wafer dic\$6		
		protect\$6 releas\$6) adj tape)) and (((die chip) adj pad)		
		leadframe (lead adj frame) ((uv ultraviolet) with adhe\$8))	_	
14	38	5480842.URPN.	USPAT	2004/08/05 14:04
15	12	("3631307" "3702464" "4266334" "4417413"	USPAT	2004/08/05 14:20
·		"4862490" "4889980" "5127984" "5250600"		
	_	"5255430" "5261999" "5311396" "5399907").PN.	LICDAT	2004/00/05 14:46
16	6	((wafer dic\$6 protect\$6 releas\$6) adj tape) same (((die	USPAT;	2004/08/05 14:46
		chip) adj pad) with (leadframe (lead adj frame) ((((package	US-PGPUB	
4.7		wiring) adj substrate) carrier) with (solder adj ball))))	LICDAT	2004/08/05 14:49
17	0	((wafer dic\$6 protect\$6 releas\$6) adj tape) same ((die chip)	USPAT;	2004/06/05 14:49
		adj pad) same (leadframe (lead adj frame)) same	US-PGPUB	
		((((package wiring) adj substrate) carrier module) with		
18	2	(solder adj ball)) ((die chip) adj pad) same (leadframe (lead adj frame)) same	USPAT;	2004/08/05 14:49
16	2	((((package wiring) adj substrate) carrier module) with	US-PGPUB	2004/00/03 14.43
		((((package wiring) adj substrate) carrier module) with (((solder adj ball))	00 10100	
_	0	kr-199969593-\$.did.	USPAT;	2004/08/04 16:59
-		- 10, 199909099 ψ.αια.	US-PGPUB;	
·			EPO; JPO;	
			DERWENT	
_	1	1998kr-0003970.ap,prai.	USPAT;	2004/07/27 09:05
	_ *		US-PGPUB;	
			EPO; JPO;	
			DERWENT	

-	 2023	(semiconductor wafer package chip ic integrated die dice	USPAT;	2004/08/05 09:07
		silicon) with tape with apparatus	US-PGPUB	2004/00/04 47:02
-	1808	, , , , , , , , , , , , , , , , , , , ,	USPAT;	2004/08/04 17:02
i		tape with apparatus	US-PGPUB	